

L Number	Hits	Search Text	DB	Time stamp
1	92	<b>assembly and apparatus and solder adj ball near placing</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:33</b>
2	4	<b>assembly and apparatus and solder adj ball near placing and hopper and substrate</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:29</b>
3	2	<b>assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:32</b>
4	2	<b>("4256532"   "5880017").PN.</b>	<b>USPAT</b>	<b>2004/06/15 14:31</b>
5	2	<b>assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:32</b>
6	2	<b>assembly and apparatus and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:33</b>
7	0	<b>assembly and apparatus and hopper and substrate near stencil and 29/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:33</b>
8	247	<b>assembly and apparatus and solder adj ball and 29/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:34</b>
9	0	<b>assembly and apparatus and solder adj ball and 29/\$.ccls. and stencil and hopper</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:35</b>
10	1	<b>assembly and apparatus and solder adj ball and 29/\$.ccls. and hopper</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/15 14:36</b>

11	19	assembly and apparatus and solder adj ball and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB DERWENT	2004/06/15 14:36
12	1	2001-182234.NRAN.		2004/06/15 14:40

	<b>Title</b>	<b>Current OR</b>
1	<b>System for forming contacts on a semiconductor component by aligning and attaching ferromagnetic balls</b>	228/180.21
2	<b>Fine pitch solder sphere placement</b>	438/612
3	<b>Solder-ball bonding device and method</b>	228/246
4	<b>Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus</b>	228/41
5	<b>Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus</b>	228/41
6	<b>Solder-ball bonding device and method</b>	228/246
7	<b>Apparatus for supplying solder balls</b>	406/144
8	<b>Method and system for forming contacts on a semiconductor component by aligning and attaching ferromagnetic balls</b>	228/245
9	<b>Method of making components with solder balls</b>	438/612

	<b>Title</b>	<b>Current OR</b>
10	<b>Machine-vision ring-reflector illumination system and method</b>	<b>362/247</b>
11	<b>Fluxless solder ball attachment process</b>	<b>438/615</b>
12	<b>Process for transferring material to semiconductor chip conductive pads using a transfer substrate</b>	<b>438/616</b>
13	<b>Preformed solder parts coated with parylene in a thickness effective to exhibit predetermined interference colors</b>	<b>428/212</b>
14	<b>Computer system with surface mount socket</b>	<b>439/73</b>
15	<b>Bottom-surface-metallurgy rework process in ceramic modules</b>	<b>228/119</b>
16	<b>Solder ball placement machine</b>	<b>228/41</b>
17	<b>Individual chip joining machine</b>	<b>219/85.12</b>

	<b>Title</b>	<b>Current OR</b>
18	<b>Fine pitch placement of solder spheres on components of assembly by moving solder spheres relative to stencil, pouring off remainder of solder spheres, removing the stencil and frame from base, and heating the components</b>	
19	<b>Solder ball supply smoothing appts. e.g. for semiconductor device - uses mask for positioning ball forming hole w.r.t. solder pad on circuit, with hopper dropping solder ball onto mask and squeegee pressing ball to desired height NoAbstract</b>	